

INTRODUCTION



Duo-Clasp™ 1.25mm (0.49") Pitch Dual-Row SMT Wire-to-Board System

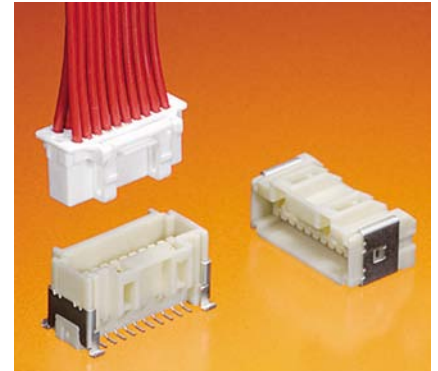
Molex's Duo-Clasp™ wire-to-board connectors offer similar positive locking features as Molex's CLIKMate™ family of connectors, with the added feature of gold plating for increased durability.

Molex's Duo-Clasp system was designed for LCD and PDP TV applications. As a 1.25mm pitch dual-row system with gold plating, Duo-Clasp now fills a niche that was missing in Molex's range of positive lock wire-to-board connectors.

Both CLIKMate and Duo-Clasp feature a dual positive lock system that provides superior mating retention compared to positive lock systems with just a single lock interface. The dual-lock design prevents the housing from being dislodged from the PCB connector in case the wires are pulled, which can cause poor signal contact. Both systems also offer a tactile "click" feel to confirm mating.

Specifications:

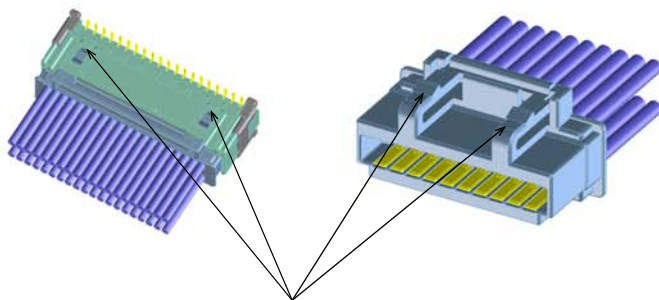
- Current: 1.0A
- Voltage: 50V
- Contact Plating: Gold
- Contact Resistance: 20 milliohms max.
- Insulation Resistance: 100 megohms min.
- Dielectric Withstanding Voltage: 500V AC
- Durability: 30 cycles
- Flammability: UL94V0
- Operating Temperature: -25 to +85°C



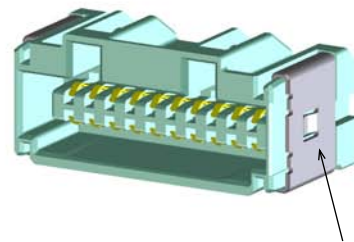
Features

Benefits

- | | |
|---|--|
| • Dual positive inner lock | • Provides better mating retention than single lock styles |
| • Bellows and leaf-style contact design | • Secure electrical contact and avoids terminal stubbing |
| • Compact dual-row 1.25mm pitch | • Space savings and high density design |
| • Reinforced metal solder tabs | • Provide strong PCB retention and strain relief for solder joints |
| • Gold plating | • Durability and secure electrical contact |



Dual positive locks provide secure mating retention



Robust metal solder tabs provide secure PCB retention and strain relief for solder joints in the event of rough extraction

MARKETS AND APPLICATIONS

- LCD and PDP TVs
- Pachinko/Gaming
- Data Communications





Duo-Clasp™
1.25mm (0.49") Pitch
Dual-Row SMT
Wire-to-Board System

Crimp Terminal

Order Number	Packaging	AWG	Insulation Diameter	Contact Material	Plating
501930-1100	Chain	26-28	0.80 to 1.00mm	Copper Alloy	Gold

Crimp Housing

Circuits	Order Number
20	503110-2010
30	503110-3010
40	503110-4010

PCB Receptacles

Circuits	Vertical Type	Right Angle Type
20	501931-2070	502046-2070
30	501931-3070	502046-3070
40	501931-4070	502046-4070

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